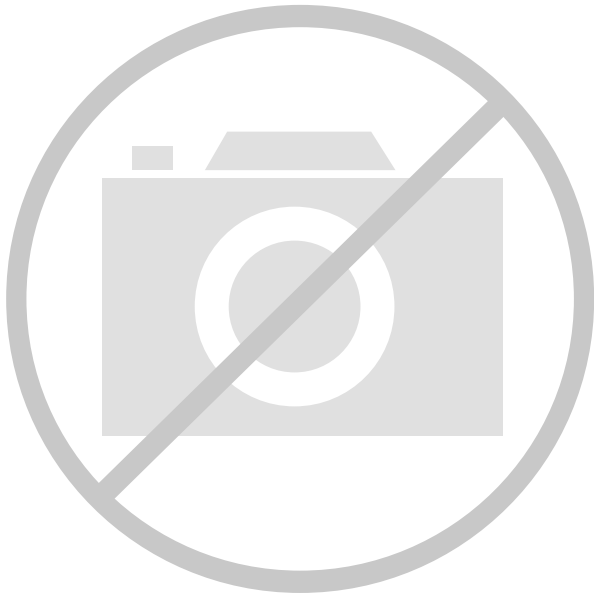




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	159
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640c-5fn256c

The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock/Control Distribution Network

The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO1200 and MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices

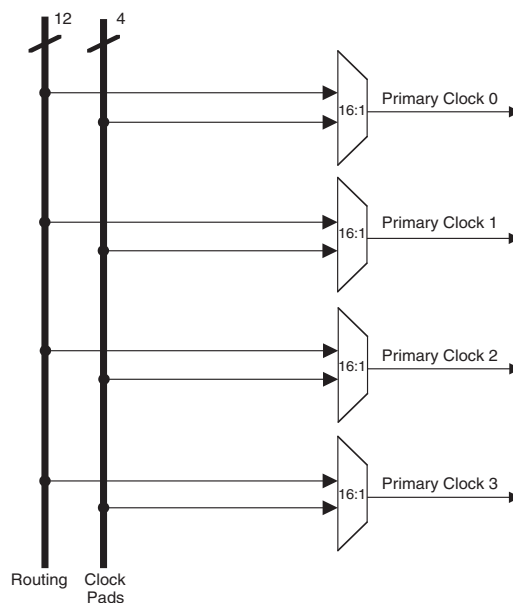
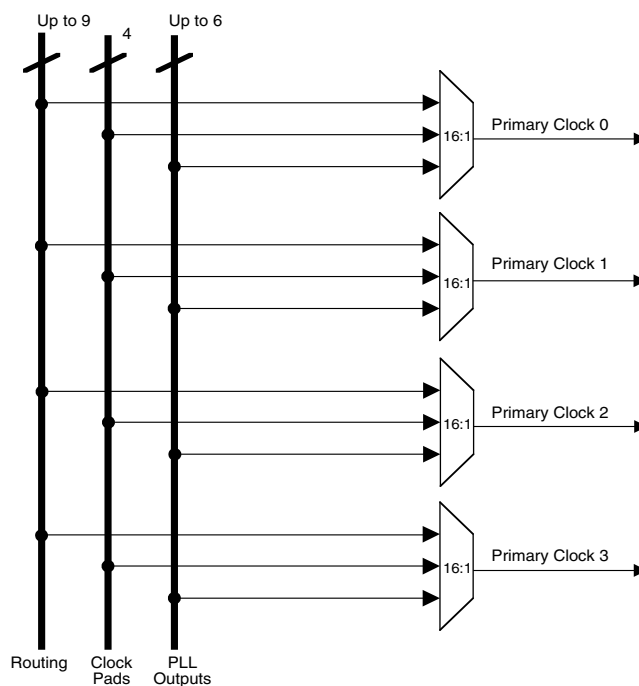
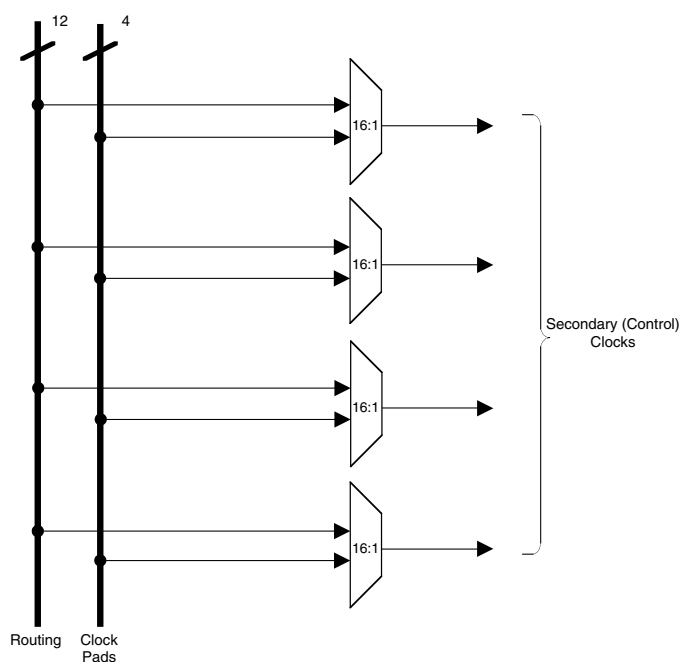


Figure 2-8. Primary Clocks for MachXO1200 and MachXO2280 Devices



Four secondary clocks are generated from four 16:1 muxes as shown in Figure 2-9. Four of the secondary clock sources come from dual function clock pins and 12 come from internal routing.

Figure 2-9. Secondary Clocks for MachXO Devices



The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

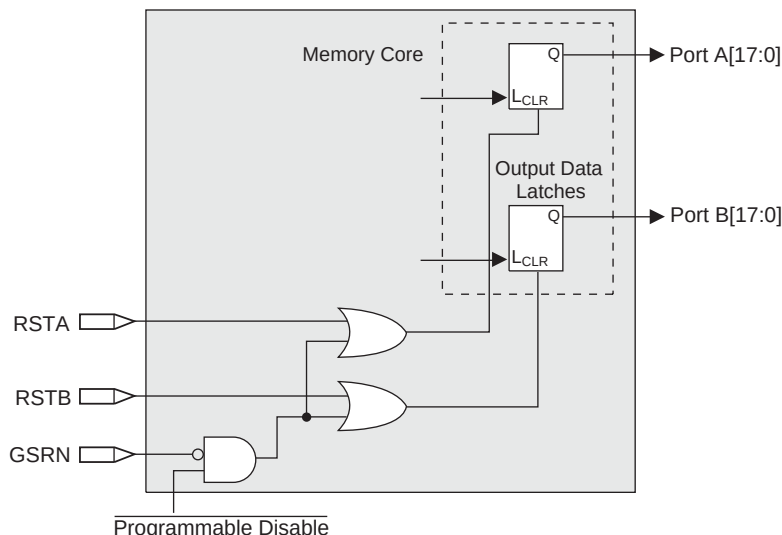
N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

Figure 2-13. Memory Core Reset

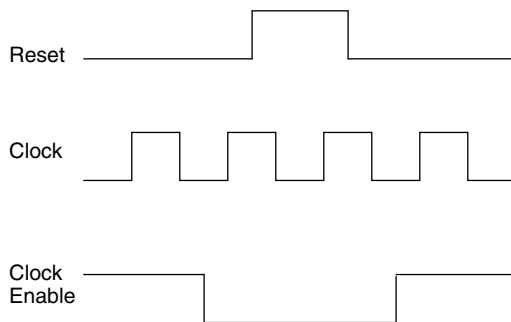


For further information on the sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-14. The GSR input to the EBR is always asynchronous.

Figure 2-14. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM and FIFO implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-14. The reset timing rules apply to the RPRreset input vs the RE input and the RST input vs. the WE and RE inputs. Both RST and RPRreset are always asynchronous EBR inputs.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled

Table 2-8. I/O Support Device by Device

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

Table 2-9. Supported Input Standards

Input Standard	VCCIO (Typ.)				
	3.3V	2.5V	1.8V	1.5V	1.2V
Single Ended Interfaces					
LVTTTL	Yes	Yes	Yes	Yes	Yes
LVC MOS33	Yes	Yes	Yes	Yes	Yes
LVC MOS25	Yes	Yes	Yes	Yes	Yes
LVC MOS18			Yes		
LVC MOS15				Yes	
LVC MOS12	Yes	Yes	Yes	Yes	Yes
PCI ¹	Yes				
Differential Interfaces					
BLVDS ² , LVDS ² , LVPECL ² , RSDS ²	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.

2. MachXO1200 and MachXO2280 devices only.

Figure 2-18. MachXO2280 Banks

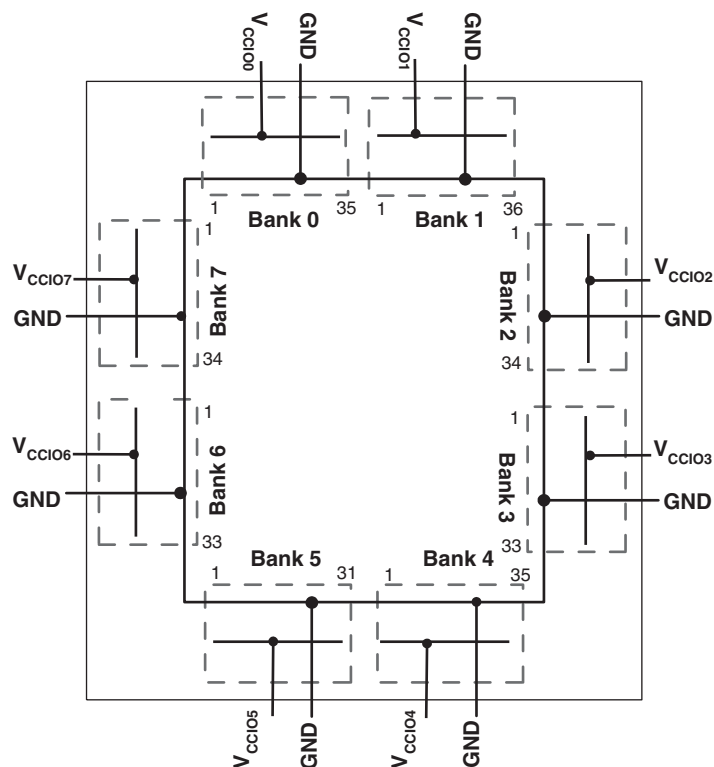
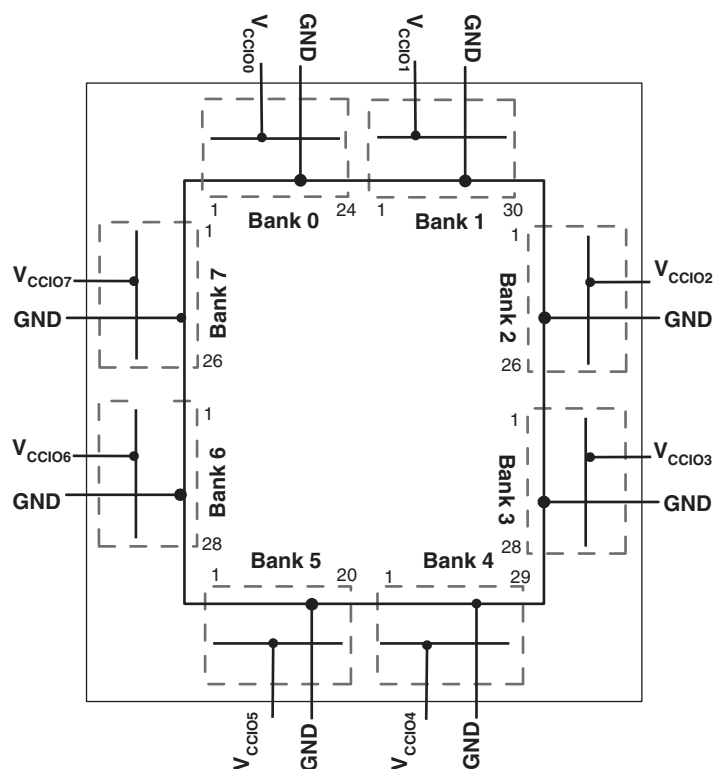


Figure 2-19. MachXO1200 Banks



For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

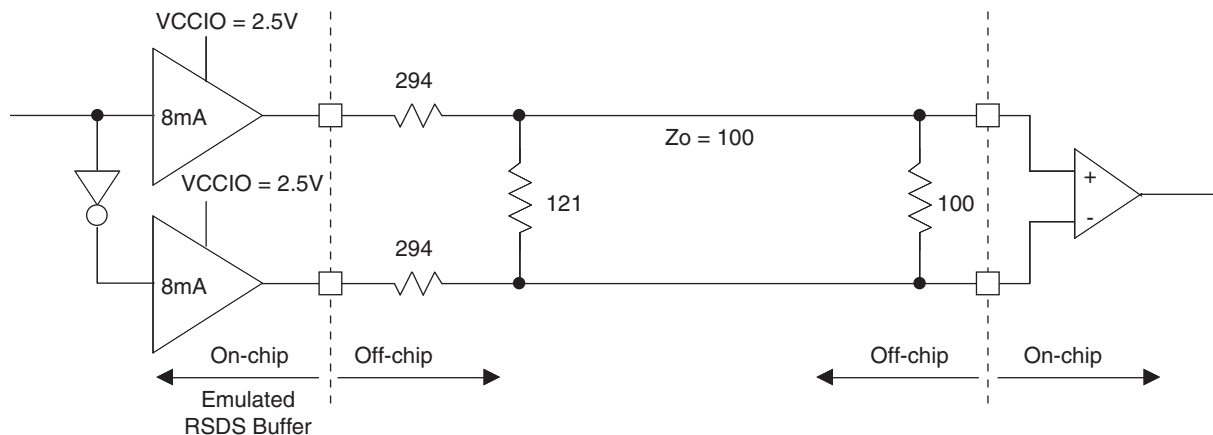


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

Typical Building Block Function Performance¹

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

Register-to-Register Performance

Function	-5 Timing	Units
Basic Functions		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
Embedded Memory Functions (1200 and 2280 Devices Only)		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
Distributed Memory Functions		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

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Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

MachXO Internal Timing Parameters¹

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t _{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t _{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t _{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t _{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t _{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t _{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t _{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t _{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t _{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t _{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t _{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t _{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t _{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t _{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t _{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t _{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t _{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t _{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t _{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t _{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t _{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t _{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t _{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t _{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t _{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t _{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t _{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t _{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

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sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f _{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
f _{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f _{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f _{VCO}	PLL VCO Frequency		420	840	MHz
f _{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
AC Characteristics					
t _{DT}	Output Clock Duty Cycle	Default duty cycle selected ³	45	55	%
t _{PH} ⁴	Output Phase Accuracy		—	0.05	UI
t _{OPJIT} ¹	Output Clock Period Jitter	f _{OUT} >= 100 MHz	—	+/-120	ps
		f _{OUT} < 100 MHz	—	0.02	UIPP
t _{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t _W	Output Clock Pulse Width	At 90% or 10% ³	1	—	ns
t _{LOCK} ²	PLL Lock-in Time		—	150	μs
t _{PA}	Programmable Delay Unit		100	450	ps
t _{IPJIT}	Input Clock Period Jitter	f _{OUT} ≥ 100 MHz	—	+/-200	ps
		f _{OUT} < 100 MHz	—	0.02	UI
t _{FBKDLY}	External Feedback Delay		—	10	ns
t _{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t _{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t _{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. CLKOS as compared to CLKOP output.

5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.

6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

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LCMX01200 and LCMX02280 Logic Signal Connections: 100 TQFP

Pin Number	LCMX01200				LCMX02280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
4	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
5	PL4B	7			PL4B	7		
6	VCCIO7	7			VCCIO7	7		
7	PL6A	7		T*	PL7A	7		T*
8	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
9	GND	-			GND	-		
10	PL7C	7		T	PL9C	7		T
11	PL7D	7		C	PL9D	7		C
12	PL8C	7		T	PL10C	7		T
13	PL8D	7		C	PL10D	7		C
14	PL9C	6			PL11C	6		
15	PL10A	6		T*	PL13A	6		T*
16	PL10B	6		C*	PL13B	6		C*
17	VCC	-			VCC	-		
18	PL11B	6			PL14D	6		C
19	PL11C	6	TSALL		PL14C	6	TSALL	T
20	VCCIO6	6			VCCIO6	6		
21	PL13C	6			PL16C	6		
22	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
23	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
24	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
25	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
26**	GNDIO6 GNDIO5	-			GNDIO6 GNDIO5	-		
27	VCCIO5	5			VCCIO5	5		
28	TMS	5	TMS		TMS	5	TMS	
29	TCK	5	TCK		TCK	5	TCK	
30	PB3B	5			PB3B	5		
31	PB4A	5		T	PB4A	5		T
32	PB4B	5		C	PB4B	5		C
33	TDO	5	TDO		TDO	5	TDO	
34	TDI	5	TDI		TDI	5	TDI	
35	VCC	-			VCC	-		
36	VCCAUX	-			VCCAUX	-		
37	PB6E	5		T	PB8E	5		T
38	PB6F	5		C	PB8F	5		C
39	PB7B	4	PCLK4_1****		PB10F	4	PCLK4_1****	
40	PB7F	4	PCLK4_0****		PB10B	4	PCLK4_0****	
41	GND	-			GND	-		

LCMX0640, LCMX01200 and LCMX02280 Logic Signal Connections: 132 csBGA (Cont.)

LCMX0640					LCMX01200					LCMX02280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

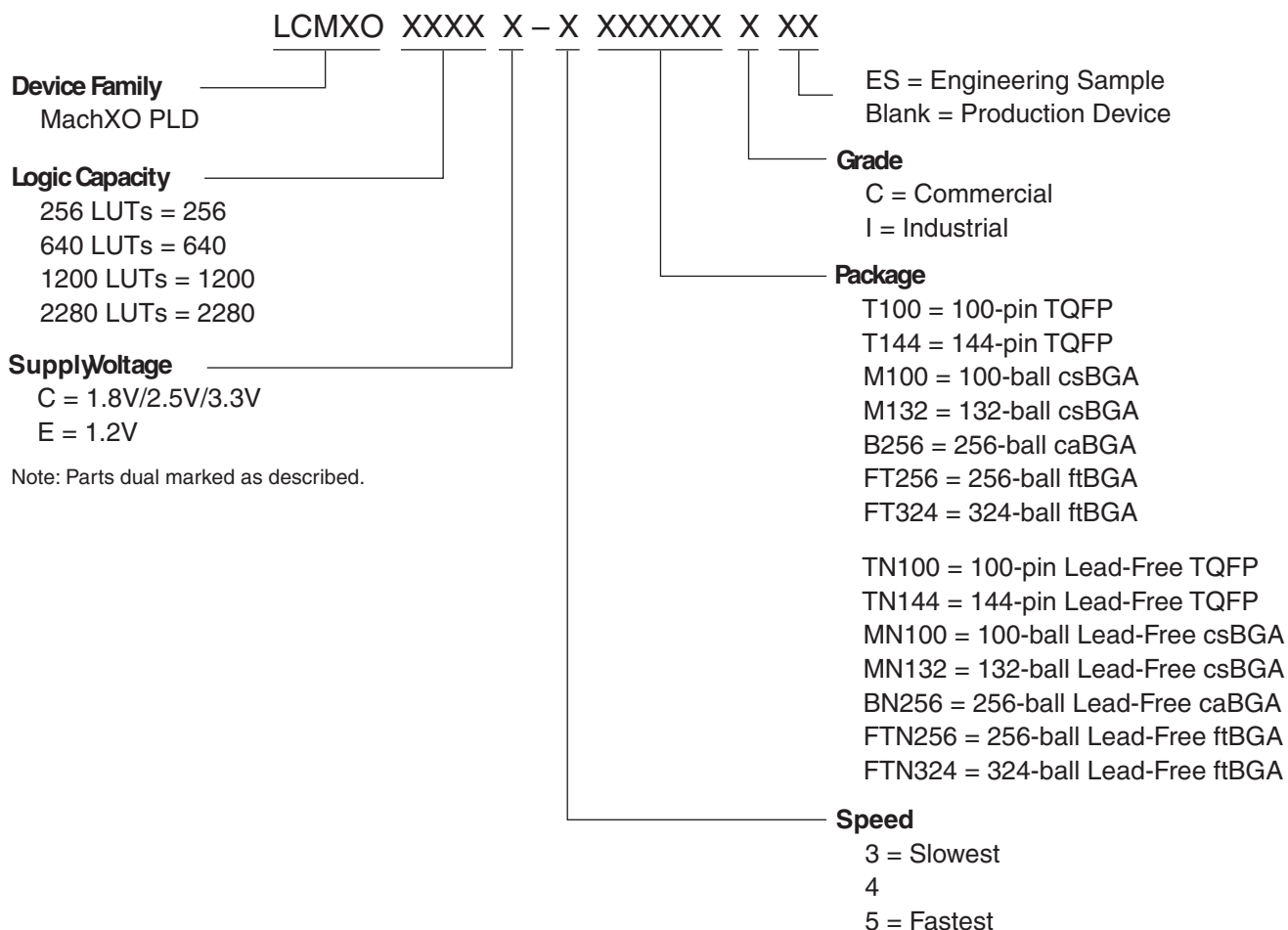
LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
D3	NC				D3	PT2C	0		T	D3	PT3C	0		T
A3	PT2B	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2A	0		T	A2	PT3A	0		T	A2	PT3A	0		T
B3	NC				B3	PT2B	0		C	B3	PT2D	0		C
B2	NC				B2	PT2A	0		T	B2	PT2C	0		T
VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0		
GND	GNDIO0	0			GND	GNDIO0	0			GND	GNDIO0	0		
A1	GND	-			A1	GND	-			A1	GND	-		
A16	GND	-			A16	GND	-			A16	GND	-		
F11	GND	-			F11	GND	-			F11	GND	-		
G8	GND	-			G8	GND	-			G8	GND	-		
G9	GND	-			G9	GND	-			G9	GND	-		
H7	GND	-			H7	GND	-			H7	GND	-		
H8	GND	-			H8	GND	-			H8	GND	-		
H9	GND	-			H9	GND	-			H9	GND	-		
H10	GND	-			H10	GND	-			H10	GND	-		
J7	GND	-			J7	GND	-			J7	GND	-		
J8	GND	-			J8	GND	-			J8	GND	-		
J9	GND	-			J9	GND	-			J9	GND	-		
J10	GND	-			J10	GND	-			J10	GND	-		
K8	GND	-			K8	GND	-			K8	GND	-		
K9	GND	-			K9	GND	-			K9	GND	-		
L6	GND	-			L6	GND	-			L6	GND	-		
T1	GND	-			T1	GND	-			T1	GND	-		
T16	GND	-			T16	GND	-			T16	GND	-		
G7	VCC	-			G7	VCC	-			G7	VCC	-		
G10	VCC	-			G10	VCC	-			G10	VCC	-		
K7	VCC	-			K7	VCC	-			K7	VCC	-		
K10	VCC	-			K10	VCC	-			K10	VCC	-		
H6	VCCIO3	3			H6	VCCIO7	7			H6	VCCIO7	7		
G6	VCCIO3	3			G6	VCCIO7	7			G6	VCCIO7	7		
K6	VCCIO3	3			K6	VCCIO6	6			K6	VCCIO6	6		
J6	VCCIO3	3			J6	VCCIO6	6			J6	VCCIO6	6		
L8	VCCIO2	2			L8	VCCIO5	5			L8	VCCIO5	5		
L7	VCCIO2	2			L7	VCCIO5	5			L7	VCCIO5	5		
L9	VCCIO2	2			L9	VCCIO4	4			L9	VCCIO4	4		
L10	VCCIO2	2			L10	VCCIO4	4			L10	VCCIO4	4		
K11	VCCIO1	1			K11	VCCIO3	3			K11	VCCIO3	3		
J11	VCCIO1	1			J11	VCCIO3	3			J11	VCCIO3	3		
H11	VCCIO1	1			H11	VCCIO2	2			H11	VCCIO2	2		
G11	VCCIO1	1			G11	VCCIO2	2			G11	VCCIO2	2		
F9	VCCIO0	0			F9	VCCIO1	1			F9	VCCIO1	1		
F10	VCCIO0	0			F10	VCCIO1	1			F10	VCCIO1	1		
F8	VCCIO0	0			F8	VCCIO0	0			F8	VCCIO0	0		
F7	VCCIO0	0			F7	VCCIO0	0			F7	VCCIO0	0		

* Supports true LVDS outputs.

** NC for "E" devices.

*** Primary clock inputs are single-ended.

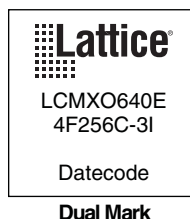
Part Number Description



Note: Parts dual marked as described.

Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device. For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade. The slowest commercial speed grade does not have industrial markings. The markings appears as follows:



Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3T100C	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMXO2280C-4T100C	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMXO2280C-5T100C	2280	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMXO2280C-3T144C	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO2280C-4T144C	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO2280C-5T144C	2280	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO2280C-3M132C	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO2280C-4M132C	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO2280C-5M132C	2280	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO2280C-3B256C	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMXO2280C-4B256C	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMXO2280C-5B256C	2280	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMXO2280C-3FT256C	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMXO2280C-4FT256C	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMXO2280C-5FT256C	2280	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM
LCMXO2280C-3FT324C	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	COM
LCMXO2280C-4FT324C	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	COM
LCMXO2280C-5FT324C	2280	1.8V/2.5V/3.3V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100C	256	1.2V	78	-3	TQFP	100	COM
LCMXO256E-4T100C	256	1.2V	78	-4	TQFP	100	COM
LCMXO256E-5T100C	256	1.2V	78	-5	TQFP	100	COM
LCMXO256E-3M100C	256	1.2V	78	-3	csBGA	100	COM
LCMXO256E-4M100C	256	1.2V	78	-4	csBGA	100	COM
LCMXO256E-5M100C	256	1.2V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100C	640	1.2V	74	-3	TQFP	100	COM
LCMXO640E-4T100C	640	1.2V	74	-4	TQFP	100	COM
LCMXO640E-5T100C	640	1.2V	74	-5	TQFP	100	COM
LCMXO640E-3M100C	640	1.2V	74	-3	csBGA	100	COM
LCMXO640E-4M100C	640	1.2V	74	-4	csBGA	100	COM
LCMXO640E-5M100C	640	1.2V	74	-5	csBGA	100	COM
LCMXO640E-3T144C	640	1.2V	113	-3	TQFP	144	COM
LCMXO640E-4T144C	640	1.2V	113	-4	TQFP	144	COM
LCMXO640E-5T144C	640	1.2V	113	-5	TQFP	144	COM
LCMXO640E-3M132C	640	1.2V	101	-3	csBGA	132	COM
LCMXO640E-4M132C	640	1.2V	101	-4	csBGA	132	COM
LCMXO640E-5M132C	640	1.2V	101	-5	csBGA	132	COM
LCMXO640E-3B256C	640	1.2V	159	-3	caBGA	256	COM
LCMXO640E-4B256C	640	1.2V	159	-4	caBGA	256	COM
LCMXO640E-5B256C	640	1.2V	159	-5	caBGA	256	COM
LCMXO640E-3FT256C	640	1.2V	159	-3	ftBGA	256	COM
LCMXO640E-4FT256C	640	1.2V	159	-4	ftBGA	256	COM
LCMXO640E-5FT256C	640	1.2V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMXO256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMXO256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMXO256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMXO640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMXO640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMXO640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMXO640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMXO640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMXO640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMXO640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMXO640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMXO640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMXO640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMXO640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMXO1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMXO1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMXO1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMXO1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMXO1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMXO1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMXO1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMXO1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMXO1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMXO2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMXO2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMXO2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMXO2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMXO2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMXO2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMXO2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMXO2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMXO2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMXO2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMXO2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, [MachXO sysIO Usage Guide](#)
- TN1089, [MachXO sysCLOCK Design and Usage Guide](#)
- TN1092, [Memory Usage Guide for MachXO Devices](#)
- TN1090, [Power Estimation and Management for MachXO Devices](#)
- TN1086, [MachXO JTAG Programming and Configuration User's Guide](#)
- TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#)
- TN1097, [MachXO Density Migration](#)
- AN8066, [Boundary Scan Testability with Lattice sysIO Capability](#)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTTL, LVCMOS): www.jedec.org
- PCI: www.pcisig.com

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timing updated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

Date	Version	Section	Change Summary
November 2006	02.3	DC and Switching Characteristics	Corrections to MachXO “C” Sleep Mode Timing table - value for $t_{WSLEEPN}$ (400ns) changed from max. to min. Value for t_{WAWAKE} (100ns) changed from min. to max.
			Added Flash Download Time table.
December 2006	02.4	Architecture	EBR Asynchronous Reset section added.
		Pinout Information	Power Supply and NC table; Pin/Ball orientation footnotes added.
February 2007	02.5	Architecture	Updated EBR Asynchronous Reset section.
August 2007	02.6	DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics table.
November 2007	02.7	DC and Switching Characteristics	Added JTAG Port Timing Waveforms diagram.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
June 2009	02.8	Introduction	Added 0.8-mm 256-pin caBGA package to MachXO Family Selection Guide table.
		Pinout Information	Added Logic Signal Connections table for 0.8-mm 256-pin caBGA package.
		Ordering Information	Updated Part Number Description diagram and Ordering Part Number tables with 0.8-mm 256-pin caBGA package information.
July 2010	02.9	DC and Switching Characteristics	Updated sysCLOCK PLL Timing table.
June 2013	03.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.
		DC and Switching Characteristics	MachXO1200 and MachXO2280 Hot Socketing Specifications table – Removed footnote 4.
			Added MachXO Programming/Erase Specifications table.